



Material Content Data Sheet



Sales Product Name		IPB180N04S3-02		Issued		26. September 2017		
MA#		MA000361815						
Package		PG-TO263-7-3		Weight*		1542.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.237	0.79	0.79	7935	7935
leadframe	non noble metal	iron	7439-89-6	0.803	0.05		521	
	inorganic material	phosphorus	7723-14-0	0.241	0.02		156	
	non noble metal	copper	7440-50-8	801.714	51.97	52.04	519849	520527
wire	non noble metal	aluminium	7429-90-5	134.730	8.74	8.74	87363	87363
encapsulation	organic material	carbon black	1333-86-4	6.990	0.45		4532	
	plastics	epoxy resin	-	76.886	4.99		49855	
	inorganic material	silicondioxide	60676-86-0	382.099	24.78	30.22	247763	302150
leadfinish	non noble metal	tin	7440-31-5	12.317	0.80	0.80	7986	7986
plating	non noble metal	nickel	7440-02-0	0.269	0.02		175	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	1	175
solder	noble metal	silver	7440-22-4	0.189	0.01		123	
	non noble metal	tin	7440-31-5	0.151	0.01		98	
	non noble metal	lead	7439-92-1	7.224	0.47	0.49	4684	4905
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		69	
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	copper	7440-50-8	106.210	6.89	6.90	68869	68959
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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